

Abstract

The problem of the present invention is to provide an insulation film capable of highly universal use for the production of semiconductor packages of different sizes and shapes.

5 The present invention relates to an insulation film for providing an insulation substrate carrying a semiconductor chip of a semiconductor package. Insulation film 10 of the present invention is provided with rows of opposing sprocket holes 12 formed on either edge of the above mentioned insulation film, and through holes 14 are provided disposed two-dimensionally between the rows of sprocket holes 12. Pitch p between through holes 14 is determined by the relationship $m p = n L$ (i.e., n and m are integers, and $n < m$), wherein pitch of the sprocket holes is taken to be L . The above mentioned through holes 14 are selectively utilized during formation of the desired circuit pattern upon insulation film 10 according to size of the manufactured semiconductor package.

[Selected Figure] FIG. 1